



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



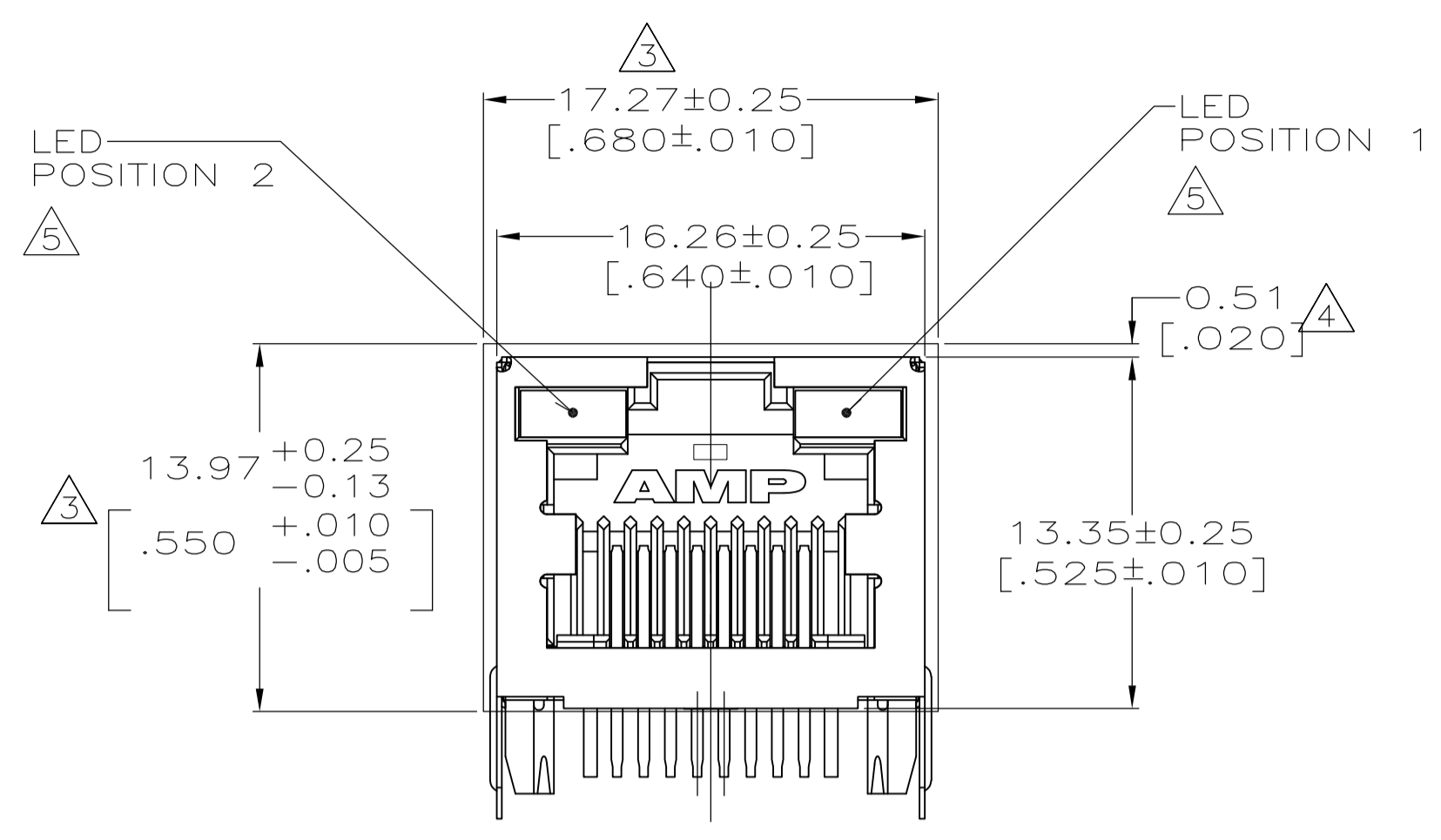
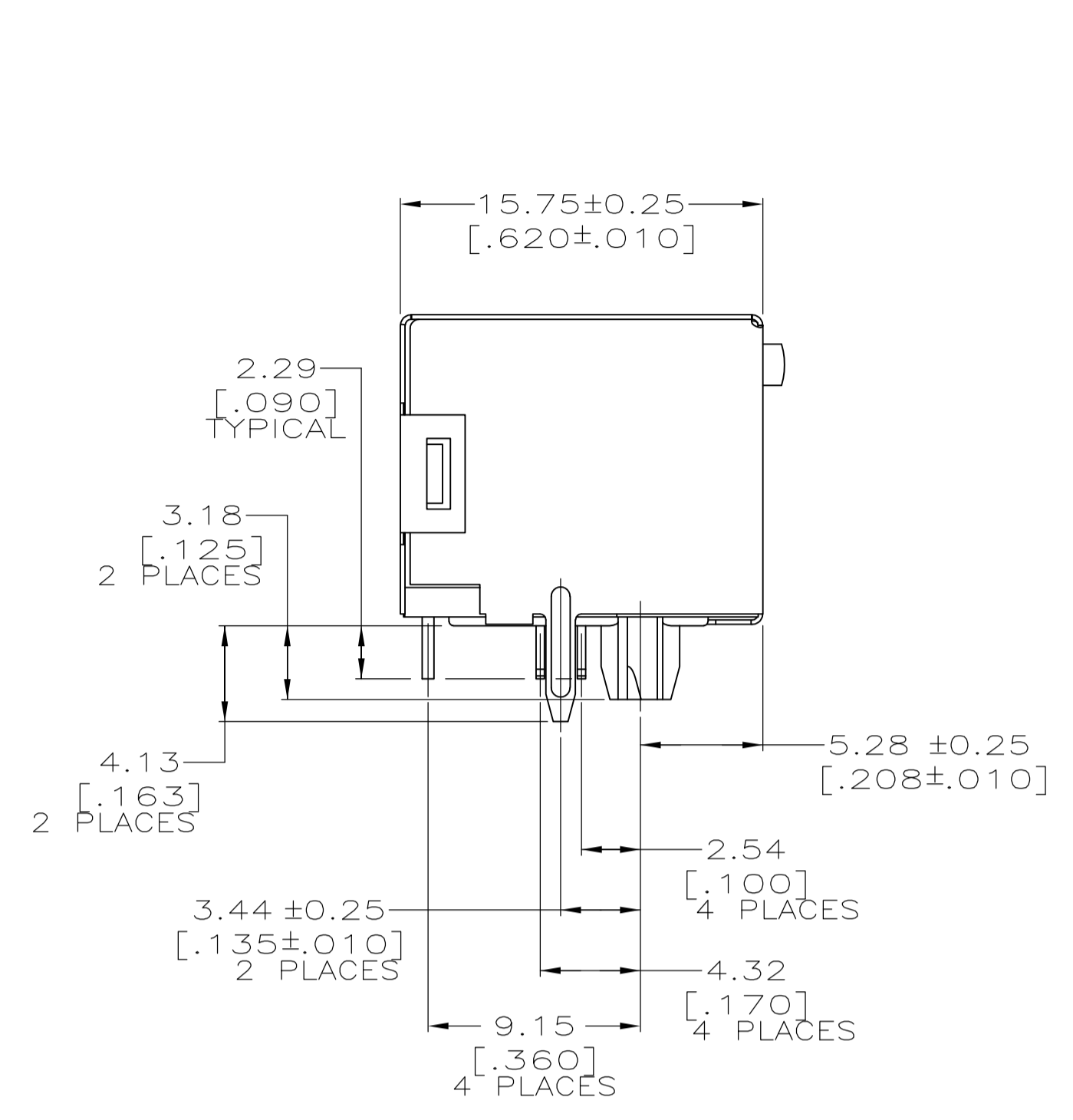
## Contact us

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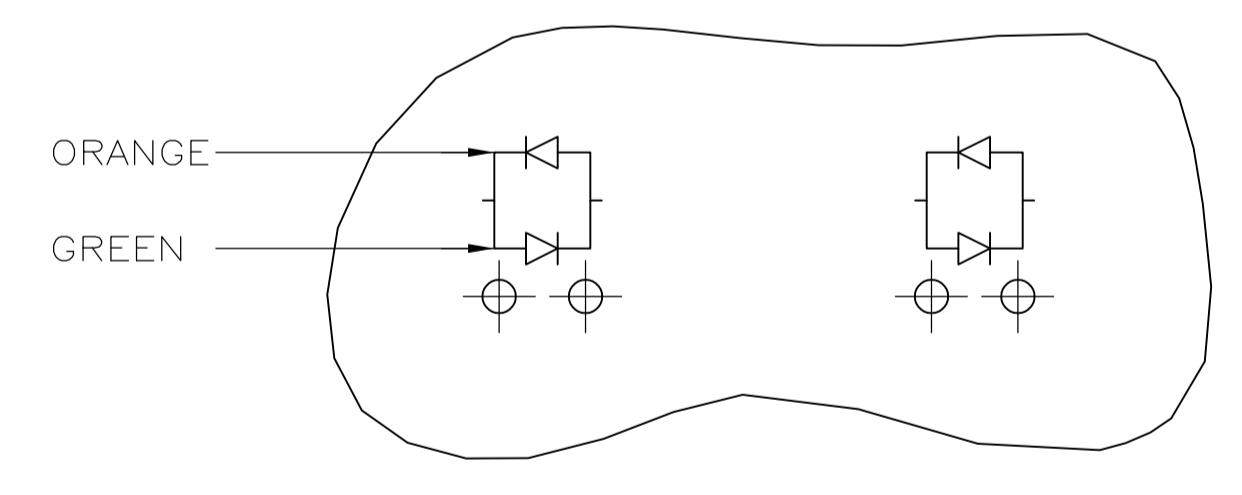
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



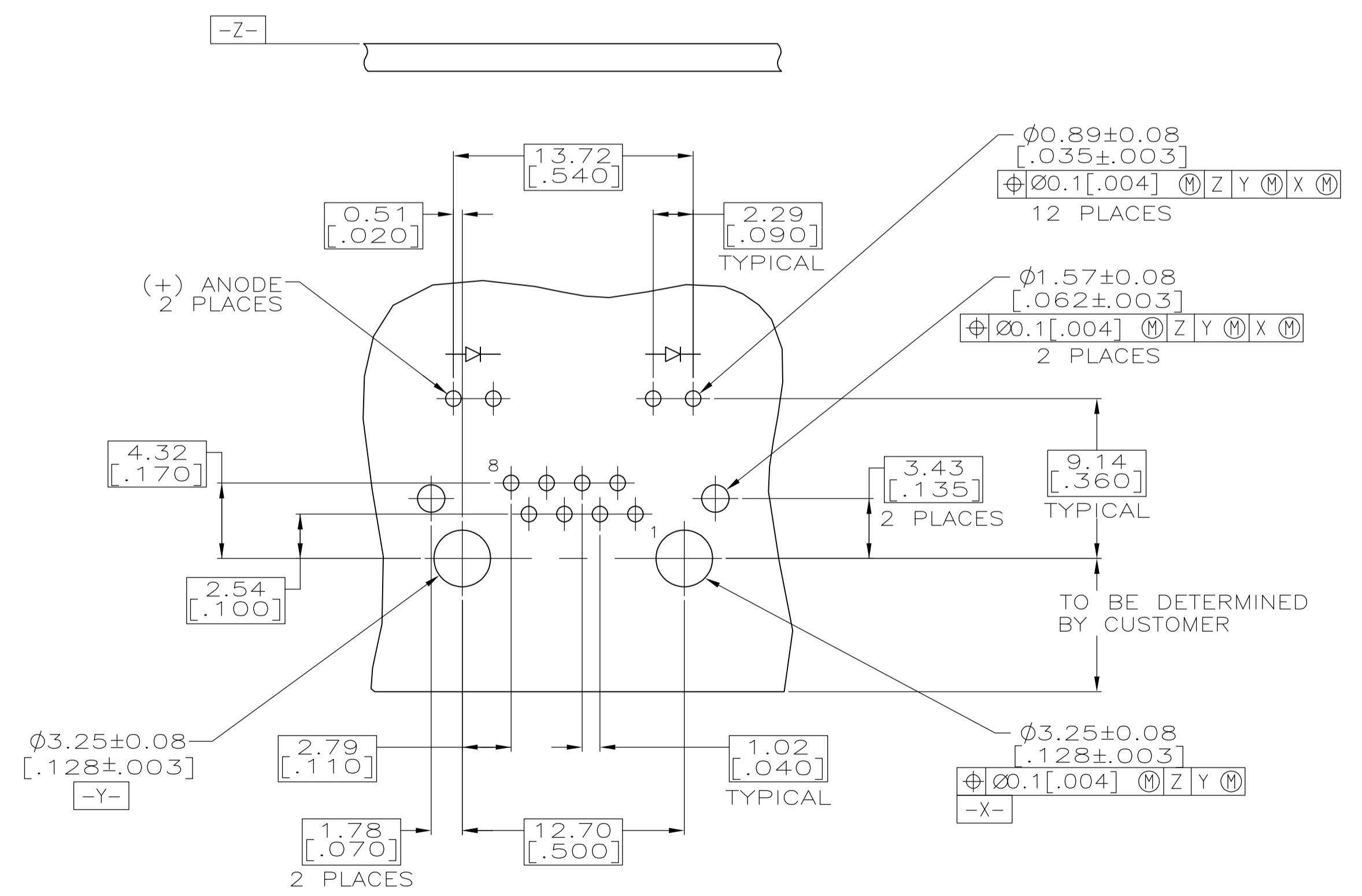


△ MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - 0.36 THICK PHOS BRONZE PLATED WITH 3.81 μm MIN THICK MATTE TIN IN SOLDER AREA. 1.27 μm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27 μm MIN THICK NICKEL.  
 SHIELD - 0.196 THICK COPPER ZINC ALLOY PREPLATED WITH 1.27 μm MIN SATIN NICKEL WITH 2.03 μm MIN TIN POST DIPPED ON PCB GROUND TABS.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51 CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 μm THICK Sn/Cu OVER 2.03 μm THICK Ag OVER 1.02 μm THICK Cu OVER 3.56 μm THICK Ni OVER 1.02 μm THICK Cu UNDERPLATE

- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



LED CURRENT DIAGRAM  
1116075-7 ONLY



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT  
(COMPONENT SIDE)

INDICATOR COLOR	INDICATOR COLOR	PART NUMBER
ORANGE/GREEN	ORANGE/GREEN	6116075-7
YELLOW	YELLOW	6116075-6
GREEN	GREEN	6116075-5
GREEN	YELLOW	6116075-4
YELLOW	-	6116075-3
-	GREEN	6116075-2
YELLOW	GREEN	6116075-1
POSITION 2	POSITION 1	

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN T. SPRINKLE / A. MAYER 30APR2005	CHK J. WESTMAN 30APR2005	APVD S. FLICKINGER 30APR2005	NAME
0 PLC ± -	1 PLC ± -	2 PLC ± 0.25[.01]	3 PLC ± 0.13[.005]	4 PLC ± -	ANGLES ± -
SEE NOTE 1	SEE NOTE 1	PRODUCT SPEC	114-2154	APPLICATION SPEC	108-1163-4
		WEIGHT	-	SIZE	CAGE CODE
				DRAWING NO	RESTRICTED TO
				A1 00779	6116075
				CUSTOMER DRAWING	SCALE 4:1 SHEET 1 OF 1 REV A1

**STE** TE Connectivity  
 INVERTED MODULAR JACK ASSEMBLY, 1X1, SHIELDED, LED